

The second circuit board 38 is fixed to the inner bottom surface of the sub-casing 32 by screwing a plurality of metal fixing members 41. The fixing members 41 divide the second circuit board 38 into a plurality of areas. Although not shown in the drawings, the frequency converter 20 and the band-pass filters 21 and 23 among the circuit components of the hybrid power-amplifier circuit 3 are each mounted on the corresponding areas of the second circuit board 38. A probe 42 as the output terminal 26 protrudes into the second waveguide groove 40 of the sub-casing 32 from one end of the second circuit board 38. Because of the requirement for providing a large amplification, all the other circuit components, i.e., the power amplifiers 22, 24 and 25, comprise bare semiconductor chips 43. These bare semiconductor chips 43 are inserted in the corresponding through-holes 38a provided in the second circuit board 38, are bonded to the inner bottom surface of the sub-casing 32 with a conductive adhesive, and are connected to a conductive pattern (not shown) on the second circuit board 38 by wire bonding.

Please rewrite the paragraph beginning on page 13, line 13 and ending on page 14, line 17 as follows: (Fig. 4)

The radiation plate 33 has a protrusion 33a, the width of which is formed slightly smaller than that of the opening 30a of the main casing 30. The sub-casing 32 and the radiation plate 33 are integrally bonded at the bottom of the sub-casing 32 and the top of the protrusion 33a, a radiation sheet 44 being interposed therebetween, thus forming the unified radiator 31 as described above. The adhesive radiation sheet 44 composed of, e.g., a silicone based resin, smoothes fine irregularities on the contact surface between the sub-casing 32 and the radiation plate 33. As shown in Fig. 7, while being inserted into the opening 30a, the radiator 31 is screwed to the bottom of the main casing 30 such that slight gaps G are maintained between the sidewalls of the protrusion 33a of the radiation plate 33 and those of the opening 30a of the main casing 30 in order that the protrusion 33a of the radiation plate 33 does not come into contact with the main casing 30. Further, as shown in Fig. 8, the main casing 30 has pluralities of depressions 45 and projections 46 which are alternately formed on the bottom of the main casing 30 with the opening 30a interposing therebetween. The projections 46 serve as contact surfaces between the bottom of the main casing 30 and the radiation plate 33 so as to join the main casing 30 and the radiation plate 33. The depressions 45, each